

	Type	Hits	Search Text
1	BRS	6	(stack\$3 with chip) and (dummy with board\$3 with pad)
2	BRS	0	(stack\$3 with chip) and (heat adj transfer adj wire)
3	BRS	27	(stack\$3 with chip) and (heat with transfer with wire)
4	BRS	17	(chip with pack\$3 with stack\$3) and ((heat near (transfer\$3 or dissipati\$3)) with wire)
5	BRS	60	(chip with stack\$3) and ((heat near (transfer\$3 or dissipati\$3)) with wire)
6	BRS	3	(chip with atop) same (conductiv\$3 near wire)
7	BRS	0	((chip with stack\$3) same adhesive same (wire with between))
8	BRS	404	(chip with stack\$3) same adhesive same wire
9	BRS	105	(chip with stack\$3) same adhesive same (wire with between)
10	BRS	1826	(semiconduct\$3 with stack\$3) and (wire with between)
11	BRS	1445	((semiconduct\$3 with stack\$3) and (wire with between)) and chip
12	BRS	219	((semiconduct\$3 with stack\$3) and (wire with between)) and chip) and (heat adj (conduct\$3 or transfer\$3))
13	BRS	347	(stack\$3 with chip) and encapsulat\$3 and (heat adj sink)
14	BRS	283	((stack\$3 with chip) and encapsulat\$3 and (heat adj sink)) and wire\$3
15	BRS	252	((semiconduct\$3 with package) same stack\$3) and chip and (heat adj (transfer\$3 or conduct\$3))
16	BRS	231	((semiconduct\$3 with package) same stack\$3) and (heat adj (transfer\$3 or conduct\$3)) and wire\$3
17	BRS	10	((semiconduct\$3 with package) same stack\$3) and (heat adj (transfer\$3 or conduct\$3)) and wire\$3) and dummy

Day : Thursday
Date: 10/28/2004

Time: 16:32:05

PALM INTRANET

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Appln Info

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Petition Info

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